
2SJ76, 2SJ77, 2SJ78, 2SJ79

Silicon P-Channel MOS FET

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Application

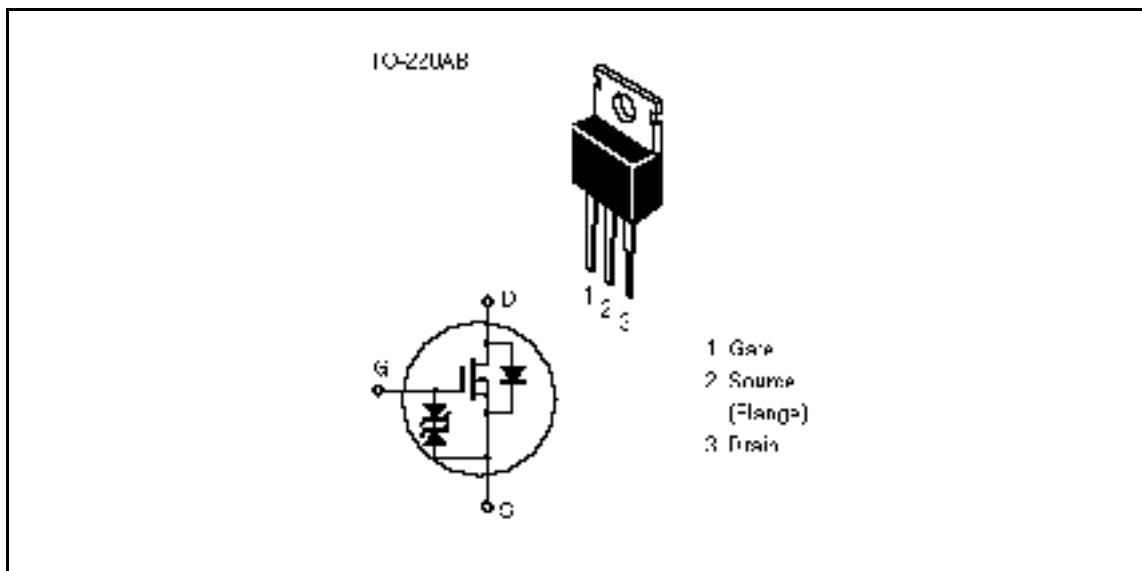
High frequency and low frequency power amplifier, high speed power switching

Complementary pair with 2SK213, 2SK214, 2SK215, 2SK216

Features

- Suitable for direct mounting
- High forward transfer admittance
- Excellent frequency response
- Enhancement-mode

Outline



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Absolute Maximum Ratings (Ta = 25°C)

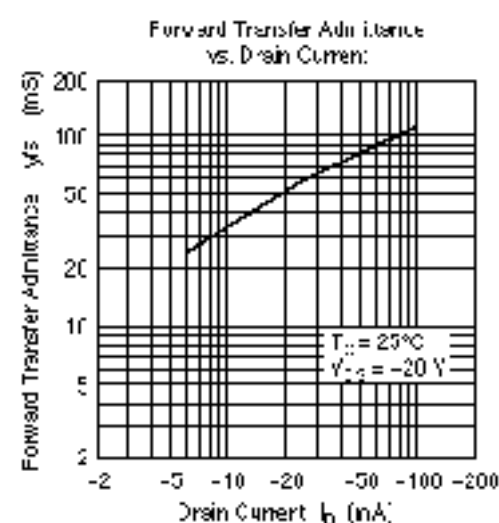
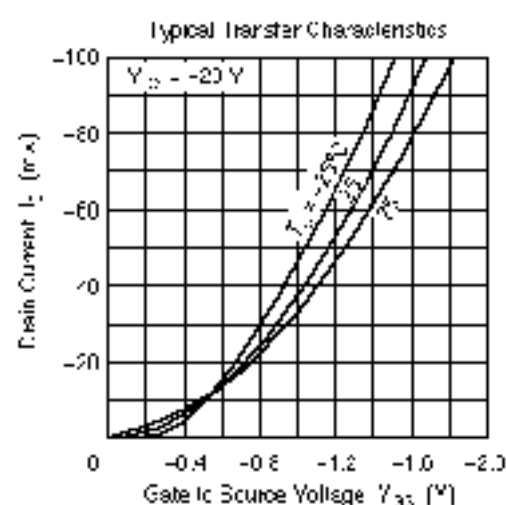
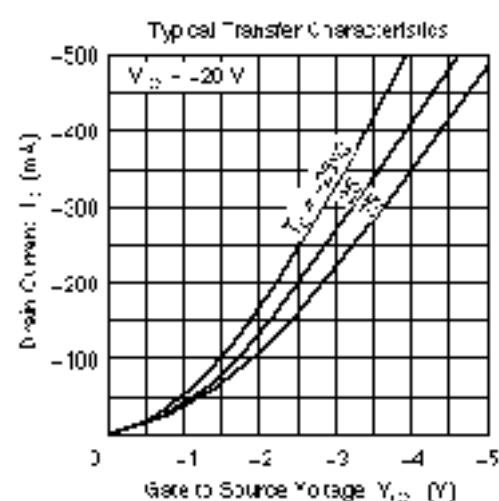
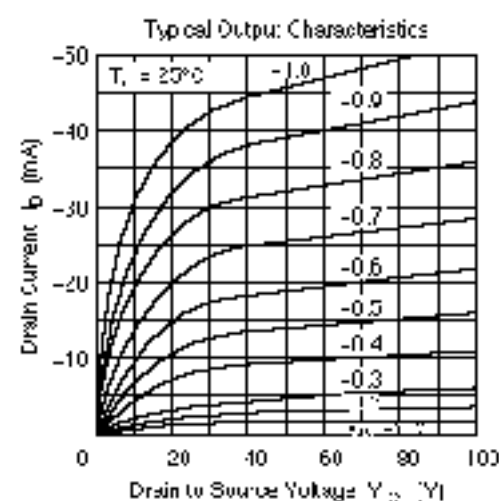
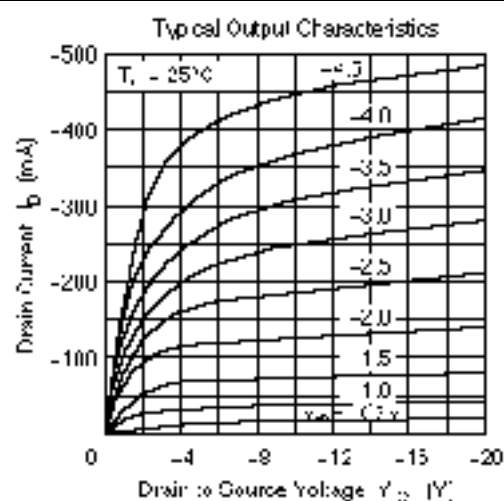
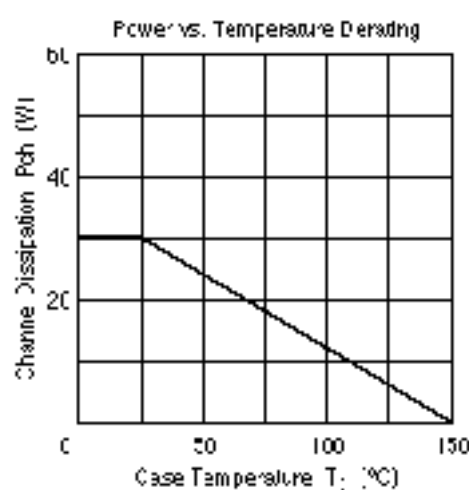
Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSX}	-140	V
		-160	
		-180	
		-200	
Gate to source voltage	V_{GSS}	±15	V
Drain current	I_D	-500	mA
Body to drain diode reverse drain current	I_{DR}	-500	mA
Channel dissipation	Pch	1.75	W
	Pch* ¹	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-45 to +150	°C

Note: 1. Value at T_C = 25°C

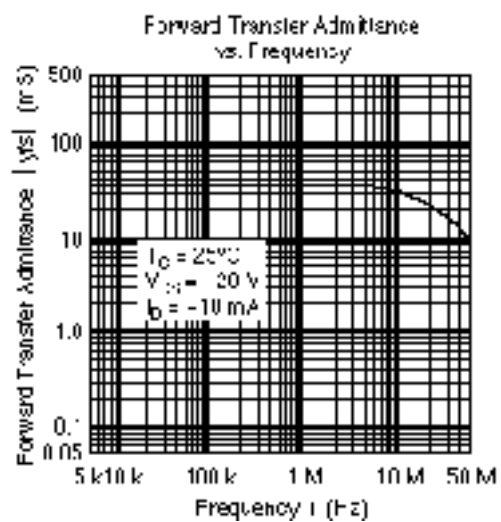
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSX}$	-140	—	—	V	$V_{GS} = 2 \text{ V}, I_D = -1 \text{ mA}$
		-160	—	—	V	
		-180	—	—	V	
		-200	—	—	V	
Gate to source breakdown voltage	$V_{(BR)GSS}$	±15	—	—	V	$I_G = \pm 10 \mu\text{A}, V_{DS} = 0$
Gate to source voltage	$V_{GS(on)}$	-0.2	—	-1.5	V	$I_D = -10 \text{ mA}, V_{DS} = -10 \text{ V}^{*1}$
Drain to source saturation voltage	$V_{DS(sat)}$	—	—	-2.0	V	$I_D = -10 \text{ mA}, V_{GD} = 0^{*1}$
Forward transfer admittance	$ y_{fs} $	20	35	—	mS	$I_D = -10 \text{ mA}, V_{DS} = -20 \text{ V}^{*1}$
Input capacitance	Ciss	—	120	—	pF	$V_{DS} = -10 \text{ V}, I_D = -10 \text{ mA},$
Reverse transfer capacitance	Crss	—	4.8	—	pF	$f = 1 \text{ MHz}$

Note: 1. Pulse test



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